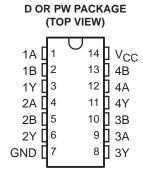
SN74ALVC08-Q1 QUADRUPLE 2-INPUT POSITIVE-AND GATE

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- Qualified for Automotive Applications
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Operates From 1.65 V to 3.6 V
- Max t_{pd} of 2.9 ns at 3.3 V
- ±24-mA Output Drive at 3.3 V
- Latch-Up Performance Exceeds 250 mA Per JESD 17



description/ordering information

The SN74ALVC08 quadruple 2-input positive-AND gate is designed for 1.65-V to 3.6-V V_{CC} operation.

The device performs the Boolean function $Y = A \bullet B$ or $Y = \overline{A + B}$ in positive logic.

ORDERING INFORMATION†

TA	PACKAGE [‡]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
4000 1- 0500	SOIC - D	Tape and reel	SN74ALVC08IDRQ1	ALVC08I
-40°C to 85°C	TSSOP – PW	Tape and reel	SN74ALVC08IPWRQ1	VA08I

[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

FUNCTION TABLE (each gate)

INP	JTS	OUTPUT
Α	В	Y
Н	Н	Н
L	Χ	L
X	L	L

logic diagram, each gate (positive logic)





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



[‡] Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}	0.5 V to 4.6 V
Input voltage range, V _I (see Note 1)	0.5 V to 4.6 V
Output voltage range, V _O (see Notes 1 and 2)	\dots -0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$)	
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, IO	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ _{JA} (see Note 3): D package	86°C/W
PW package	113°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. This value is limited to 4.6 V maximum.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
Vcc	Supply voltage		1.65	3.6	V	
		V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}			
VIH	High-level input voltage	V _{CC} = 2.3 V to 2.7 V	1.7		V	
		V _{CC} = 2.7 V to 3.6 V	2			
		V _{CC} = 1.65 V to 1.95 V		$0.35 \times V_{CC}$		
VIL	/IL Low-level input voltage	V _{CC} = 2.3 V to 2.7 V		0.7	V	
		V _{CC} = 2.7 V to 3.6 V		0.8]	
VI	Input voltage		0	3.6	V	
٧o	Output voltage		0	VCC	V	
		V _{CC} = 1.65 V		-4		
		V _{CC} = 2.3 V		-12	^	
ЮН	High-level output current	V _{CC} = 2.7 V		-12	mA	
		V _{CC} = 3 V		-24		
		V _{CC} = 1.65 V		4		
		V _{CC} = 2.3 V		12	mA	
lOL	Low-level output current	V _{CC} = 2.7 V		12		
	V _{CC} = 3 V			24		
Δt/Δν	Input transition rise or fall rate	•		5	ns/V	
TA	Operating free-air temperature		-40	85	°C	
	All conversed imports of the planting provet has been at 1					

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CO	ONDITIONS	v _{cc}	MIN	TYP [†]	MAX	UNIT
	I _{OH} = -100 μA		1.65 V to 3.6 V	V _{CC} -0.	2		
	$I_{OH} = -4 \text{ mA}$	1.65 V	1.2				
	I _{OH} = -6 mA		2.3 V	2			
VOH			2.3 V	1.7			V
	$I_{OH} = -12 \text{ mA}$		2.7 V	2.2			
		3 V	2.4				
	I _{OH} = -24 mA		3 V	2			
	I _{OL} = 100 μA		1.65 V to 3.6 V			0.2	
	I _{OL} = 4 mA	1.65 V			0.45		
V ₂ .	I _{OL} = 6 mA	2.3 V			0.4	٧	
VOL	L ₁ 42 m Δ	2.3 V			0.7	V	
	I _{OL} = 12 mA	2.7 V			0.4		
	I _{OL} = 24 mA	3 V			0.55		
IĮ	$V_I = V_{CC}$ or GND		3.6 V			±5	μΑ
Icc	$V_I = V_{CC}$ or GND,	IO = 0	3.6 V			10	μΑ
ΔICC	One input at V _{CC} – 0.6 V,	Other inputs at V _{CC} or GND	3 V to 3.6 V			750	μΑ
Ci	$V_I = V_{CC}$ or GND		3.3 V		4.5		pF

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

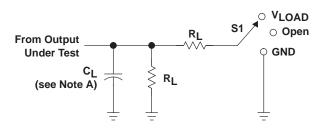
switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO (OUTPUT)	V _{CC} =		V _{CC} =		V _{CC} =	2.7 V	V _{CC} =		UNIT
	(INPUT)	(INPUT) (OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A or B	Υ	1.2	5.3	1	3.2		3	1	2.9	ns

operating characteristics, T_A = 25°C

PARAMETER		TEST CONDITIONS		V _{CC} = 1.8 V V _{CC} = 2.5 V V _{CC}		$V_{CC} = 3.3 \text{ V}$	LINUT
				TYP	TYP	TYP	UNIT
C _{pd}	Power dissipation capacitance per gate	$C_{L} = 0$,	f = 10 MHz	24	25	26	pF

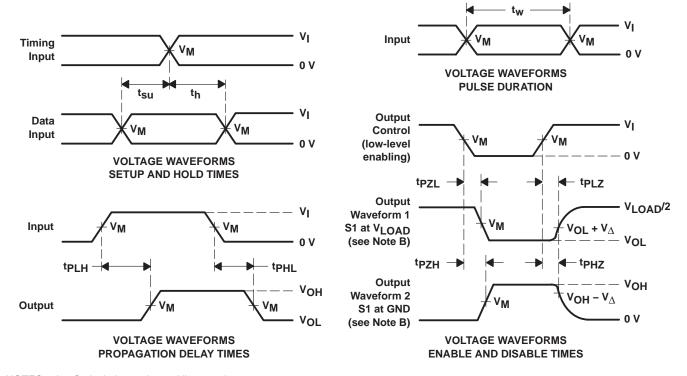
PARAMETER MEASUREMENT INFORMATION



TEST	S1
^t pd	Open
tPLZ ^{/t} PZL	V _{LOAD}
tPHZ ^{/t} PZH	GND

LOAD CIRCUIT

W	IN	PUT	V	V		D.	.,
VCC	٧ _I	t _r /t _f	VΜ	VLOAD	CL	RL	$v_{\scriptscriptstyle\Delta}$
1.8 V ± 0.15 V	VCC	≤ 2 ns	V _{CC} /2	2×V _{CC}	30 pF	1 k Ω	0.15 V
2.5 \pm 0.2 V	VCC	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V \pm 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{O} = 50 \Omega$.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzI and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms







.com 18-Sep-2008

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74ALVC08IDRG4Q1	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVC08IDRQ1	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR Level-1-235C-UNLIM
SN74ALVC08IPWRG4Q1	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVC08IPWRQ1	ACTIVE	TSSOP	PW	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN74ALVC08-Q1:

Enhanced Product: SN74ALVC08-EP

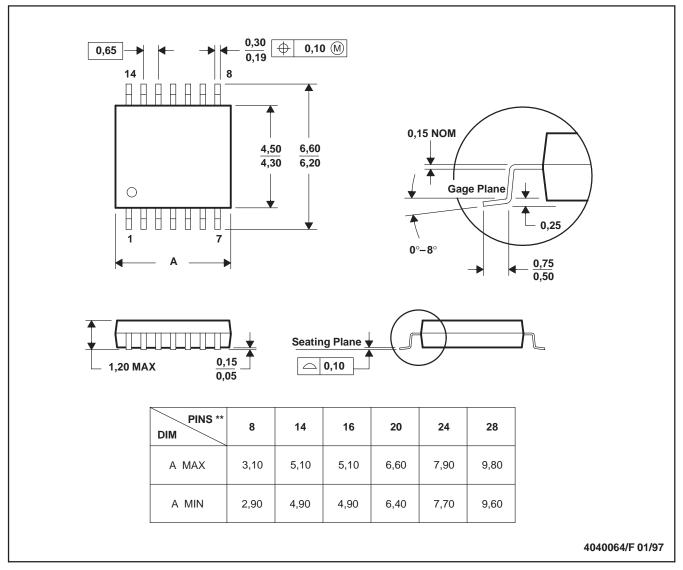
NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Enhanced Product Supports Defense, Aerospace and Medical Applications

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

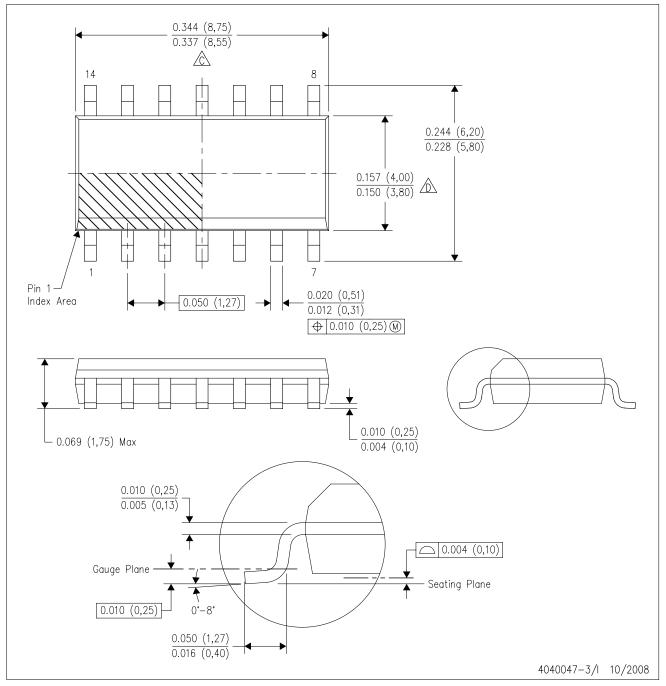
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AB.



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